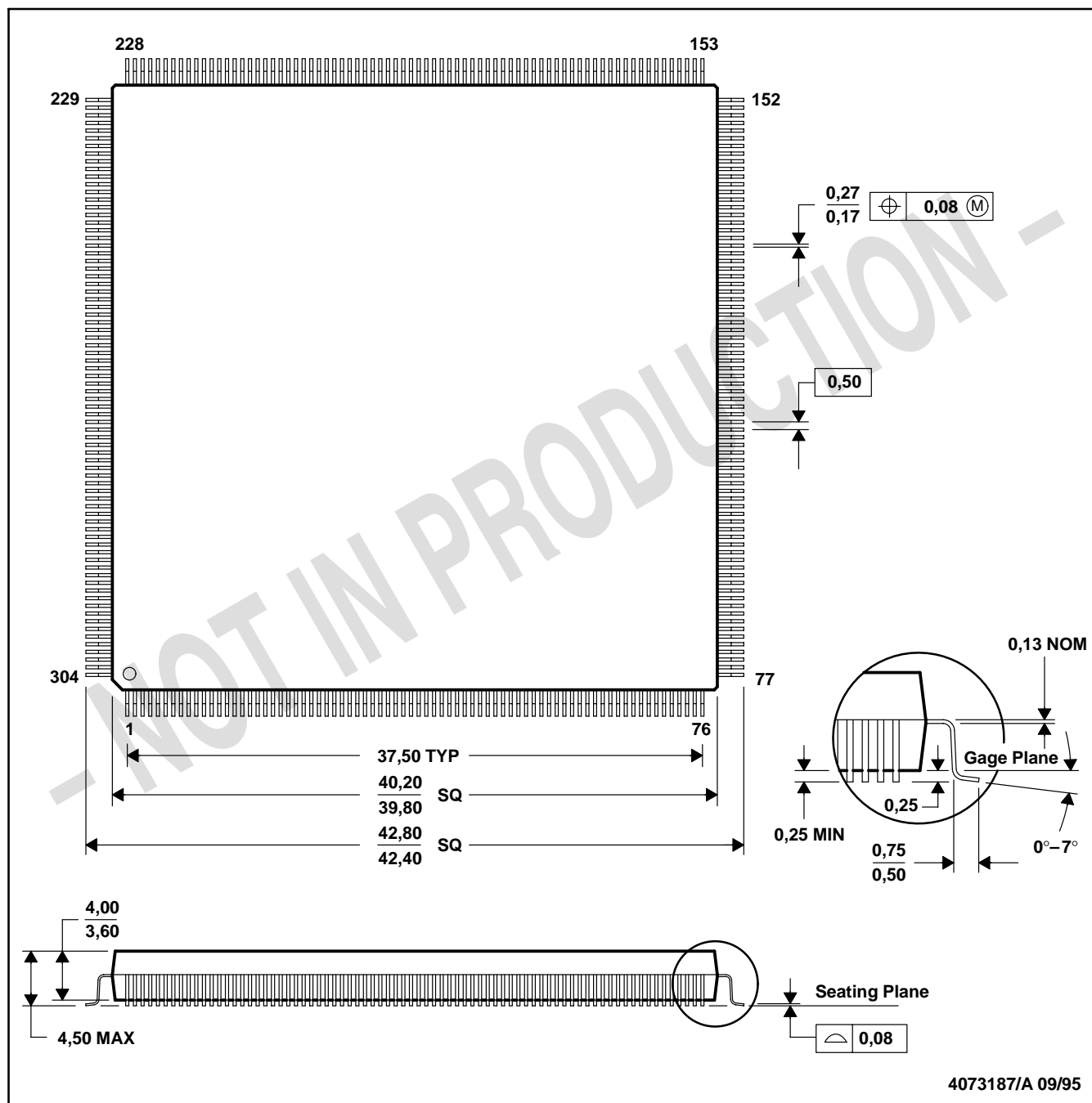


## PDE (S-PQFP-G304)

## PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Thermally enhanced molded plastic package with a heat spreader (HSP).  
 D. Falls within JEDEC MO-143

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